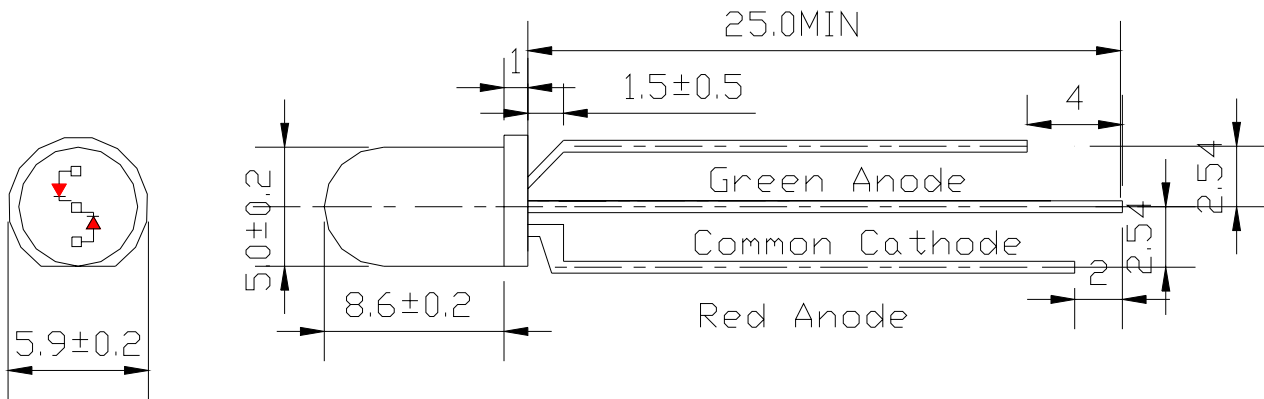


## ★ Package Dimensions



### NOTE:

1. All dimensions are in millimeter.
2. Lead spacing is measured where the lead emerge from the package.

## ★ Selection Guide

Part NO.	Chip		Lens Color	Viewing Angle $2\theta$ 1/2(deg)
	Material	Emmited Color		
5-22-WD0EY	GaAsP/GaP	Hi-Eff Red	White diffused	30
	GaAsP/GaP	Yellow		

Part No: 5-22-WD0EY

## ★Absolute Maximum Ratings

(Ta=25°C)

Parameter	Symbol	MAX. Rating	Unit
Power Dissipation	Pd	80	mW
Continuous Forward Current	IF	30	mA
Pak forward current (10 μs Pulse)	IFM	100	mA
Reverse Voltage	VR	5.0	V
Operating Temperature	Topr	-40~+105	°C
Storage Temperature	Tstg	-40~+105	°C
Lead Soldering Temperature (1.6mm From Case Bottom 260°C For 5 SEC)			

## ★Electric-Optical Characteristics

Parameter	Symbol	Test Condition	MIN	TYP	MAX	Unit
Forward Voltage	VF	IF=20mA		2.1	2.6	V
Reverse Voltage	VR	IR=10uA	5			V
Luminous Intensity	IV	IF=20mA	5	10		mcd
Peak Emission Wavelength	λ P	IF=20mA		585		nm
Spectrum Width Of Half Value	△ λ	IF=20mA		30		nm

## ★Characteristics Diagrams

